

Amendments to the Claims:

A clean version of the entire set of pending claims (including amendments to the claims, if any) is submitted herewith per 37 CFR 1.121(c)(3). This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A circuit, comprising:
a circuit board;
an electronic component having an enclosure that protects the electronic component mounted on the circuit board; and
a heat-conducting structure that surrounds the enclosure and that reduces a thermal drift of the electronic component by increasing immediately adjacent to the electronic component and increasing a thermal mass of the electronic component so as to reduce a thermal drift of the electronic component,
wherein the electronic component controls a frequency of a signal used by the circuit.
2. (Cancelled)
3. (Currently Amended) The circuit of claim 1, wherein the structure comprises a metal case around the ~~enclosure~~electronic component.
4. (Currently Amended) The circuit of claim 1, wherein the structure comprises a ceramic case around the ~~enclosure~~electronic component.
5. (Cancelled)
6. (Currently Amended) The circuit of claim 1, further comprising ~~an~~ a thermal insulator that encases the structure.

7-11. (Cancelled)

12. (Original) The circuit of claim 1, wherein the circuit is an oscillator circuit.

13. (Original) The circuit of claim 1, wherein the circuit is a clock circuit.

14. (Previously Presented) The circuit of claim 13, further comprising:

means for communication via a network;

means for synchronizing a local time value in the clock circuit in response to a set of messages transferred via the network.

15. (Currently Amended) A distributed system having a set of nodes, each node comprising:

~~a local clock including a crystal component having an enclosure that protects the crystal component;~~

~~a heat-conducting structure that surrounds immediately adjacent to the enclosure crystal component and increasing a thermal mass of the crystal component so as to reduce that reduces a thermal drift of the crystal component by increasing a thermal mass of the crystal component.~~

16. (Cancelled)

17. (Currently Amended) The distributed system of claim 15, wherein the structure comprises a metal case around the ~~enclosure~~crystal component.

18. (Currently Amended) The distributed system of claim 15, wherein the structure comprises a ceramic case around the ~~enclosure~~crystal component.

19. (Cancelled)

20. (Currently Amended) The distributed system of claim 15, further comprising ~~an~~ a thermal insulator that encases the structure.

21-27. (Canceled)

28. (New) A circuit, comprising:
a circuit board;
a crystal component mounted on the circuit board; and
means for increasing a thermal mass of the crystal component so as to reduce a thermal drift of the crystal component.

29. (New) The circuit of claim 28, wherein the means for increasing a thermal mass of the crystal component comprises a metal case adjacent to the crystal component.

30. (New) The circuit of claim 28, wherein the means for increasing a thermal mass of the crystal component comprises a ceramic case adjacent to the crystal component.

31. (New) The circuit of claim 28, further comprising a thermal insulator that encases the means for increasing the thermal mass of the crystal component.

32. (New) The circuit of claim 31, wherein the thermal insulator is styrofoam.